

Transformer



Product Specification

Product type	Specifications	Application	Dimensions(mm)
EFD15	1.20kHz-500KH	DC-DC Converter	16 0 Max 17 0 Max 13 8±0 5
	2.3.0W-12W	Driver transformer	
	325℃ to +105℃	Set-up transformer	
	4.Insulation Class:B(130℃)	Hand-held switch	
		Power supply charger	15 0 Max 16 0 Max 18 0 Max 18 0 Max 18 0 Max 18 0 Max
	1.20kHz-500KH	DC-DC Converter	21.5 Max 21.5 Max 17.5 ±0.5
	2.8.0W-30W	Driver transformer	
	325℃ to +105℃	Set-up transformer	
EFD20	4.Insulation Class:B(130℃)	Hand-held switch	21.5 Max 21.5 Max
		Power supply charger	231 25.1
	1.20kHz-500KH	DC-DC Converter	26.0 Max 27.0 Max 5±0.3
	2.15W-50W	Driver transformer	10 Max
	325℃ to +105℃	Set-up transformer	
EFD25	4.Insulation Class:B(130℃)	Hand-held switch	
		Power supply charger	26.5 Max 26.
EFD30	1.20kHz-500KH	DC-DC Converter	
	2.20W-65W	Driver transformer	31.5 Max 32.0 Max
	325℃ to +105℃	Set-up transformer	ZZ 5240 S
	4.Insulation Class:B(130℃)	Hand-held switch	
		Power supply charger	

X Special inquires besides the above common used types can be met on your requirement, Please contact your local sales.

The data is reference only. Customers should verify actual device performance in their specific applications. Specifications are subject to change without notice. Please check our website for latest information. http://www.ftind.com



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Electrial performance test

Item	Specification	Test Methods
Inductance	Refer to standard electrical spec.	HP4291B
DCR		Agilent 34401A

Reliability Performance test

Item	Specification	Test Methods
Vibration	Appearance: No damage	Test device shall be soldered on the substrate
	L change: within±10%	Oscillation Frequency: 10 to 55 to 10Hz for 1 min.
	RDC: within specification	Amplitude: 0.75 mm
	Hi-POT: within specification	Time: 2 hrs for each axis (X, Y &Z), total 6 hrs
Solderability		Pre-heating: 150°C, 1min
	90% covered with solder	Solder Composition: Sn/Ag/Cu=95.6/3.0/0.5
		Solder Temperature: 245±5°C
		Immersion Time: 4±1sec
Resistance to Soldering Heat		Pre-heating:150°C,1Min.
	Appearance: No Damage	Solder Composition: Sn/Ag/Cu=95.6/3.0/0.5
		Solder Temperature: 260±5°C
		Immersion Time: 4±1Sec.

Environmental test

Temperature Shock	Appearance: No damage	10 cycles (Air to Air) 1 cycles shall consist of:
	L change: within±10%	30 minutes exposure to −55 °C
	RDC: within specification	30 minutes exposure to 125 °C
	Hi-POT: within specification	15 seconds maximum transition between high and low temperatures
Temperature	Appearance: No damage	One cycle:
	L change: within specification	One cycle/step1: -25±3°C for 30min
	RDC: within specification	step2: 25±2°C for 3min
	Hi-POT: within specification	step3:105±3°C for 30min
Cycle		step4:25±2°C for 3min
		Total: 10 cycles
		Measured after exposure in the room condition for 24hrs
	Appearance: No damage	Temperature: 60±2°C
	L change: within specification	Relative Humidity: 90 ~ 95%
Humidity Test	RDC: within specification	Time: 96±5hrs
1031	Hi-POT: within specification	Measured after exposure in the room condition for 24hrs
		Temperature: 125±2°C
High		Time: 96±5hrs
Temperature Storage		Measured after exposure in the room condition for 24hrs
Low Temperature Storage		Temperature: -40±2°C
		Time: 96±5hrs
		Measured after exposure in the room condition for
		24hrs

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